

# Revision History - AS7C164A

Revision	Details	Date
Rev 1.0	Preliminary datasheet	November 2009
Rev 2.0	Added 28pin Skinny PDIP(300mil) package option	May 2015
Rev 3.0	Added Industrial grade	Nov. 2016
Rev 4.0	Removed 12ns speed due to poor yields can only offer 15ns	May 2017



### **FEATURES**

- ■Fast access time : 15 ns
- Low power consumption:
  Operating current : 80mA (TYP.)
  Standby current : 1mA (TYP.)
- Single 5V power supply
- All inputs and outputs TTL compatible
- ■Fully static operation
- Tri-state output
- Data retention voltage : 2.0V (MIN.)
- Green package available
- Package : 28-pin 300 mil SOJ 28-pin 300 mil Skinny P-DIP

## **GENERAL DESCRIPTION**

The AS7C164A is a 65,536-bit high speed CMOS static random access memory organized as 8,192 words by 8 bits. It is fabricated using very high performance, high reliability CMOS technology. Its standby current is stable within the range of operating temperature.

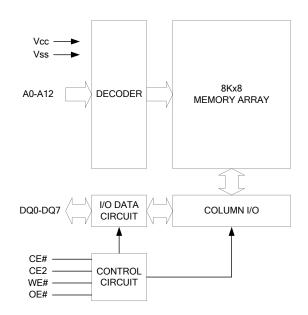
The AS7C164A is well designed for high speed system applications, and particularly well suited for battery back-up nonvolatile memory application.

The AS7C164A operates from a single power supply of 5V and all inputs and outputs are fully TTL compatible

## PRODUCT FAMILY

Product	Operating	Vcc Range	Speed	Power D	Dissipation
Family	Temperature	veerkange	opeed	Standby(IsB1,TYP.)	Operating(Icc,TYP.)
AS7C164A	(C) 0 ~ 70°C (I) -40 ~ 85°C	4.5 ~ 5.5V	15ns	1mA	90/80mA

## FUNCTIONAL BLOCK DIAGRAM

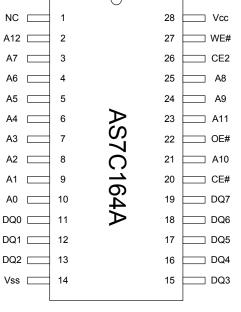


# **PIN DESCRIPTION**

SYMBOL	DESCRIPTION
A0 - A12	Address Inputs
DQ0 – DQ7	Data Inputs/Outputs
CE#, CE2	Chip Enable Inputs
WE#	Write Enable Input
OE#	Output Enable Input
Vcc	Power Supply
Vss	Ground
NC	No Connection



# **PIN CONFIGURATION**



Skinny PDIP/SOJ

### ABSOLUTE MAXIMUM RATINGS\*

PARAMETER	SYMBOL	RATING	UNIT
Voltage on Vcc relative to Vss	VT1	-0.5 to 6.5	V
Voltage on any other pin relative to Vss	Vt2	-0.5 to Vcc+0.5	V
		0 to 70(C grade)	0~
Operating Temperature	T <sup>A</sup>	-40 to 85(I grade)	°C
Storage Temperature	Tstg	-65 to 150	°C
Power Dissipation	PD	1	W
DC Output Current	Іоит	50	mA

\*Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to the absolute maximum rating conditions for extended period may affect device reliability.

## TRUTH TABLE

MODE	CE#	CE2	OE#	WE#	I/O OPERATION	SUPPLY CURRENT
Standby	Н	Х	Х	Х	High-Z	ISB1
Standby	Х	L	Х	Х	High-Z	I <sub>SB1</sub>
Output Disable	L	Н	Н	Н	High-Z	lcc
Read	L	Н	L	Н	Dout	lcc
Write	L	Н	Х	L	DIN	lcc

Note:  $H = V_{IH}$ ,  $L = V_{IL}$ , X = Don't care.



## DC ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION		MIN.	<b>TYP.</b> <sup>4</sup>	MAX.	UNIT
Supply Voltage	Vcc			4.5	5.0	5.5	V
Input High Voltage	VIH <sup>*1</sup>			2.4	-	Vcc+0.5	V
Input Low Voltage	VIL <sup>*2</sup>			- 0.5	-	0.8	V
Input Leakage Current	ILI	$V_{CC} \geqq V_{IN} \geqq V_{SS}$		- 1	-	1	μA
Output Leakage Current	Ilo	$Vcc \ge Vout \ge Vss$ , Output Disabled		- 1	-	1	μA
Output High Voltage	Vон	Іон <b>= -1mA</b>		2.4	-	-	V
Output Low Voltage	Vol	IoL = 2mA		-	-	0.4	V
Average Operating Power supply Current		Cycle time = Min. CE# = VIL and CE2 = VIH, II/o = 0mA Other pins at VIH or VIL		-	80	140	mA
Standby Power Supply Current	ISB1	$\begin{array}{l} \mbox{CE\#} \geqq V_{CC}\mbox{-}0.2V \mbox{ or } \mbox{CE2} \leqq \\ \mbox{Other pins at } 0.2V \mbox{ or } V_{CC}\mbox{-} \end{array}$		-	1	5	mA

Notes:

1.  $V_{IH}(max) = V_{CC} + 3.0V$  for pulse width less than 10ns.

2.  $V_{IL}(min) = V_{SS} - 3.0V$  for pulse width less than 10ns.

3. Over/Undershoot specifications are characterized, not 100% tested.

4. Typical values are included for reference only and are not guaranteed or tested. Typical valued are measured at V<sub>CC</sub> = V<sub>CC</sub>(TYP.) and T<sub>A</sub> =  $25^{\circ}$ C

#### **CAPACITANCE** (TA = 25°C, f = 1.0MHz)

PARAMETER	SYMBOL	MIN.	MAX	UNIT
Input Capacitance	Cin	-	6	pF
Input/Output Capacitance	Cı/o	-	8	pF

Note : These parameters are guaranteed by device characterization, but not production tested.

### **AC TEST CONDITIONS**

Input Pulse Levels	0.2V to Vcc - 0.2V
Input Rise and Fall Times	3ns
Input and Output Timing Reference Levels	1.5V
Output Load	Сь = 30pF + 1TTL, Іон/Іоь = -4mA/8mA



# **AC ELECTRICAL CHARACTERISTICS**

#### (1) READ CYCLE

PARAMETER	SYM.	AS7C1	64A-15	UNIT
		MIN.	MAX.	
Read Cycle Time	trc	15	-	ns
Address Access Time	taa	-	15	ns
Chip Enable Access Time	<b>t</b> ACE	-	15	ns
Output Enable Access Time	toe	-	7	ns
Chip Enable to Output in Low-Z	tcLz*	4	-	ns
Output Enable to Output in Low-Z	tolz*	0	-	ns
Chip Disable to Output in High-Z	tснz*	-	7	ns
Output Disable to Output in High-Z	tонz*	-	7	ns
Output Hold from Address Change	tон	3	-	ns

#### (2) WRITE CYCLE

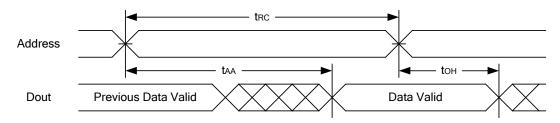
	0)/14			TINUT
PARAMETER	SYM.	AS7C1		UNIT
		MIN.	MAX.	
Write Cycle Time	twc	15	-	ns
Address Valid to End of Write	taw	12	-	ns
Chip Enable to End of Write	tcw	12	-	ns
Address Set-up Time	tas	0	-	ns
Write Pulse Width	twp	10	-	ns
Write Recovery Time	twr	0	-	ns
Data to Write Time Overlap	tow	8	-	ns
Data Hold from End of Write Time	tон	0	-	ns
Output Active from End of Write	tow*	4	-	ns
Write to Output in High-Z	twnz*	-	8	ns

\*These parameters are guaranteed by device characterization, but not production tested.

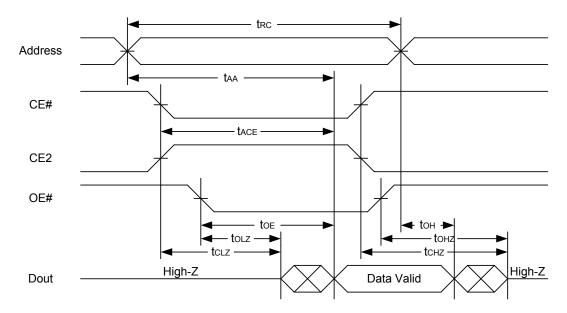


TIMING WAVEFORMS

**READ CYCLE 1** (Address Controlled) (1,2)



READ CYCLE 2 (CE# and CE2 and OE# Controlled) (1,3,4,5)



Notes :

1.WE# is high for read cycle.

2.Device is continuously selected OE# = low, CE# = low., CE2 = high.

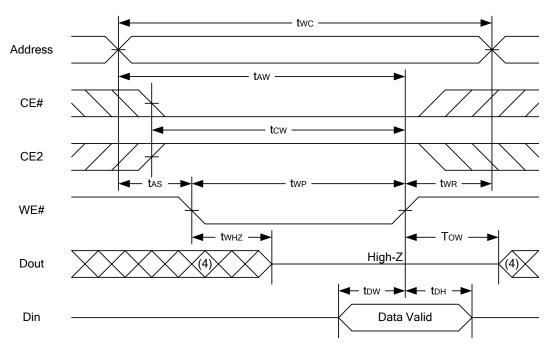
3.Address must be valid prior to or coincident with CE# = low, CE2 = high; otherwise tAA is the limiting parameter.

4.tcLz, toLz, tcHz and toHz are specified with  $C_L$  = 5pF. Transition is measured ±500mV from steady state.

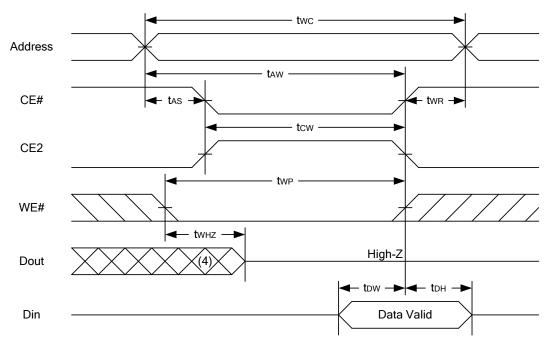
5.At any given temperature and voltage condition,  $t_{\text{CHZ}}$  is less than  $t_{\text{CLZ}}$  ,  $t_{\text{OHZ}}$  is less than  $t_{\text{OLZ}}$ .



WRITE CYCLE 1 (WE# Controlled) (1,2,3,5,6)



WRITE CYCLE 2 (CE# and CE2 Controlled) (1,2,5,6)



Notes :

- 2.A write occurs during the overlap of a low CE#, high CE2, low WE#.
- 3.During a WE#controlled write cycle with OE# low, twp must be greater than twHz + tow to allow the drivers to turn off and data to be placed on the bus.
- 4. During this period, I/O pins are in the output state, and input signals must not be applied.
- 5.If the CE#low transition and CE2 high transition occurs simultaneously with or after WE# low transition, the outputs remain in a high impedance state.
- 6.tow and twHz are specified with CL = 5pF. Transition is measured  $\pm$ 500mV from steady state.

<sup>1.</sup>WE#, CE# must be high or CE2 must be low during all address transitions.



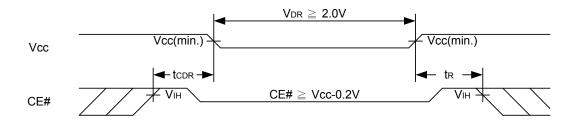
## **DATA RETENTION CHARACTERISTICS**

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Vcc for Data Retention		$\begin{array}{l} CE\# \geqq V_{CC} \text{-} 0.2V \\ or \ CE2 \leqq 0.2V \end{array}$	2.0	-	5.5	V
Data Retention Current	Idr	$\begin{array}{l} \mbox{Vcc} = 2.0\mbox{V} \\ \mbox{CE\#} \geq \mbox{Vcc} - 0.2\mbox{V} \mbox{ or } \mbox{CE2} \leq 0.2\mbox{V} \\ \mbox{Others at } 0.2\mbox{V} \mbox{ or } \mbox{V}_{\mbox{cc}} - 0.2\mbox{V} \end{array}$	-	0.6	3	mA
Chip Disable to Data Retention Time	tcdr	See Data Retention Waveforms (below)	0	-	-	ns
Recovery Time	tR		tRC∗	-	-	ns

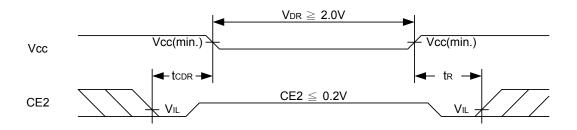
tRC∗ = Read Cycle Time

#### **DATA RETENTION WAVEFORM**

Low Vcc Data Retention Waveform (1) (CE# controlled)



#### Low Vcc Data Retention Waveform (2) (CE2 controlled)

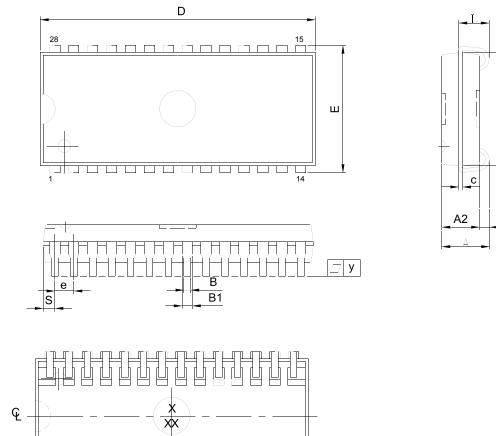




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A1

#### 28-pin 300 mil SOJ Package Outline Dimension



UNIT SYM.	INCH(REF)	MM(BASE)
A	0.140 (MAX)	3.556 (MAX)
A1	0.026 (MIN)	0.660 (MIN)
A2	0.100±0.005	2.540±0.127
В	0.018±0.003	0.457±0.076
B1	0.028 ±0.003	0.711±0.076
С	0.010±0.003	0.254±0.076
D	0.710±0.010	18.03±0.254
E	0.337±0.010	8.560±0.254
E1	0.300±0.005	7.620±0.127
е	0.050±0.003	1.270±0.076
L	0.087±0.010	2.210±0.254
S	0.030±0.004	0.762±0.102
Y	0.003 (MAX)	0.076 (MAX)

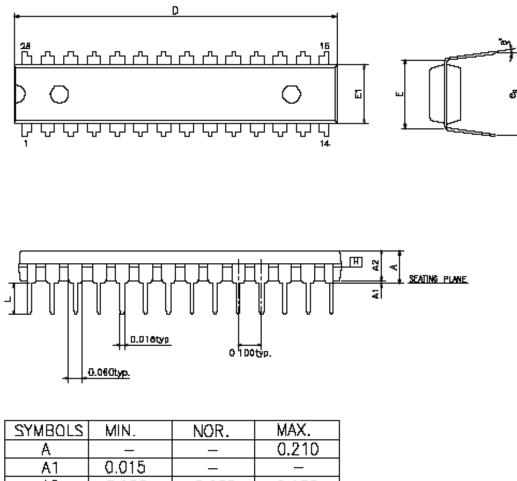
Note : 1.S/E/D dimension is not including mold flash.

2. The end flash in package lengthwise is not more than 10 mils each side.



## PACKAGE OUTLINE DIMENSION

28 pin 300 mil PDIP Package Outline Dimension



		1.011.	1010 10 34			
A	_	—	0.210			
A1	0.015	—	_			
A2	D.125	0.130	0.135			
D	1.385	1.390	1.400			
E	0.310 BSC					
E1	0.283	0.288	0.293			
L	0.115	0.130	0.150			
€ <sub>B</sub>	0.330	0.350	) 0.370			
Ð	0	7	15			
UNIT : INCH						

NOTE: 1.JEDEC OUTLINE : MS-D15 AH



#### **ORDERING INFORMATION**

Package/Access Time	Temperature	15 ns	
28-pin 300 mil SOJ	Commercial	AS7C164A-15JCN	
28-pin 300 mil Skinny P-DIP	Commercial	AS7C164A-15PCN	
28-pin 300 mil SOJ	Industrial	AS7C164A-15JIN	
28-pin 300 mil Skinny P-DIP	Industrial	AS7C164A-15PIN	

Suffix TR = tape and reel

### PART NUMBERING SYSTEM

AS7C		164A	-15	J/P	C/I	N
SRAM prefix	Voltage: 5V supply	Device Number	Access Time	J = SOJ, 300 mil P= Skinny P-DIP, 300 mil	Temperature Range: C = 0° ~ 70 °C I = -40° ~ 85° C	N = Lead Free Part



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